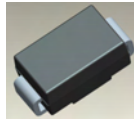


Features

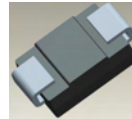
- Glass Passivated Die Construction
- Super-Fast Recovery Time For High Efficiency
- Surge Overload Rating to 35A Peak
- Ideally Suited for Automated Assembly
- **Lead Free Finish/RoHS Compliant (Note 1)**
- **Green Molding Compound (No Halogen and Antimony) (Note 2)**

Mechanical Data

- Case: SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solder Plated Terminal - Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Lead Free Plating (Matte Tin Finish).
- Polarity: Cathode Band or Cathode Notch
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.093 grams (approximate)



Top View



Bottom View

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	MURS140	MURS160	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	400	600	V
Working Peak Reverse Voltage	V _{RWM}			
DC Blocking Voltage (Note 7)	V _R			
RMS Reverse Voltage	V _{R(RMS)}	283	424	V
Average Rectified Output Current @ T _T = 135°C	I _O	1.0		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	35		A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 3)	R _{θJT}	15	°C/W
Operating Temperature Range	T _J	-55 to +150	°C
Storage Temperature Range	T _{STG}	-55 to +175	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Forward Voltage @ I _F = 1.0A, T _J = 25°C @ I _F = 1.0A, T _J = 150°C	V _{FM}	1.25 1.05	V
Peak Reverse Current @ T _A = 25°C at Rated DC Blocking Voltage (Note 7) @ T _A = 150°C	I _{RM}	5.0 150	μA
Reverse Recovery Time (Note 5)	t _{rr}	50	ns
Forward Recovery Time (Note 6)	t _{fr}	50	ns
Typical Total Capacitance (Note 4)	C _T	10	pF

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
 2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
 3. Unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.
 4. Measured at 1.0MHz and applied reverse voltage of 4V DC.
 5. Measured with I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A. See Figure 5.
 6. Measured with I_F = 1.0A, di/dt = 100A/μs, Duty Cycle ≤ 2.0%.
 7. Short duration pulse test used to minimize self-heating effect.

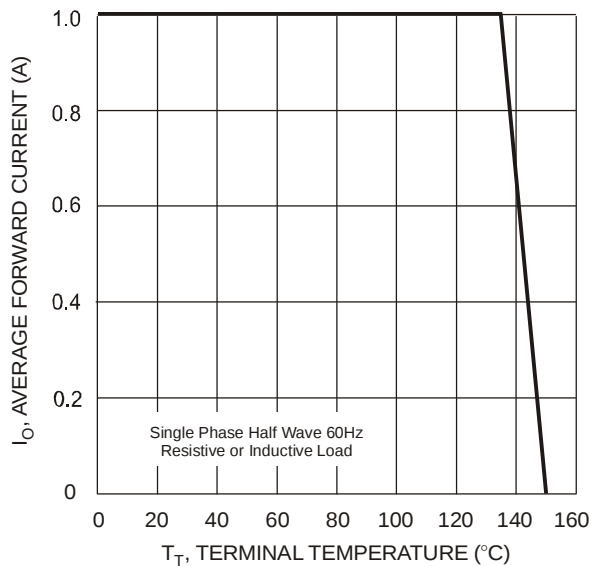


Fig. 1 Forward Current Derating Curve

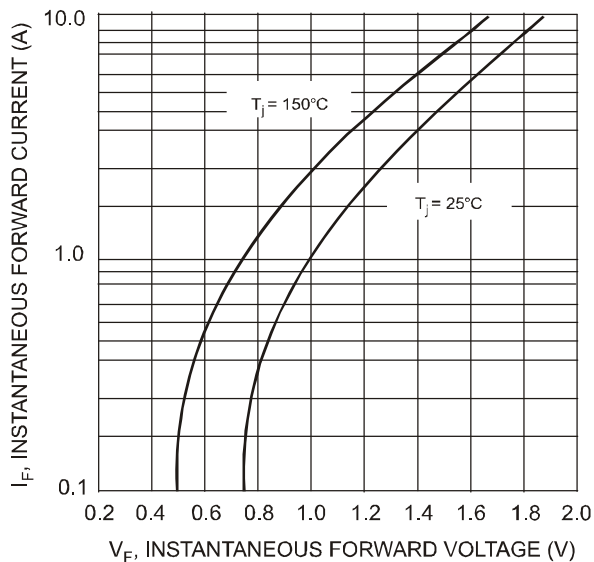


Fig. 2 Typical Forward Characteristics

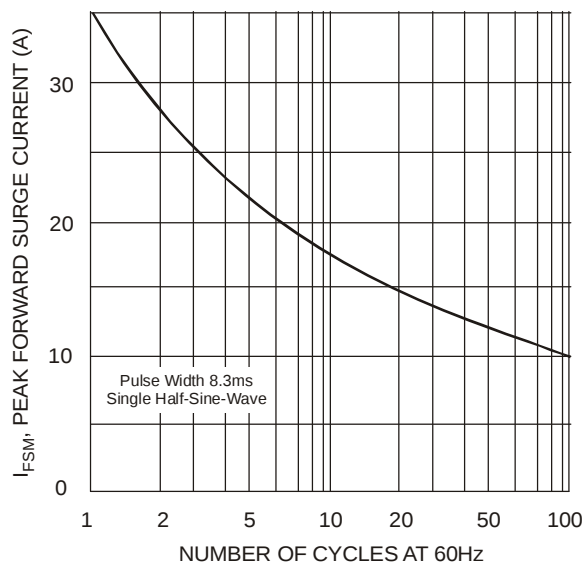


Fig. 3 Surge Current Derating Curve

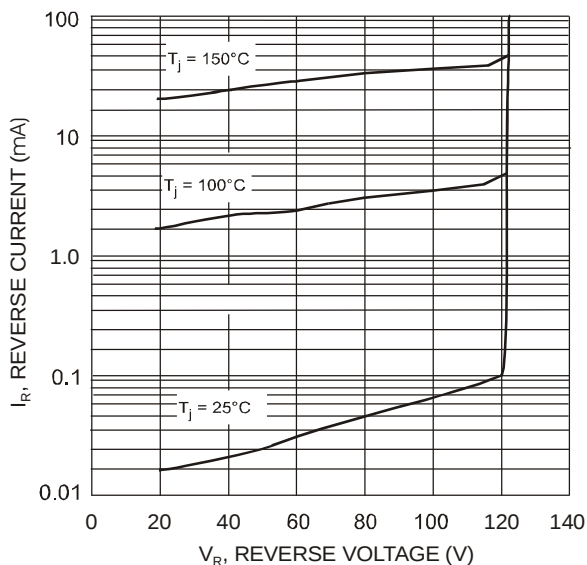
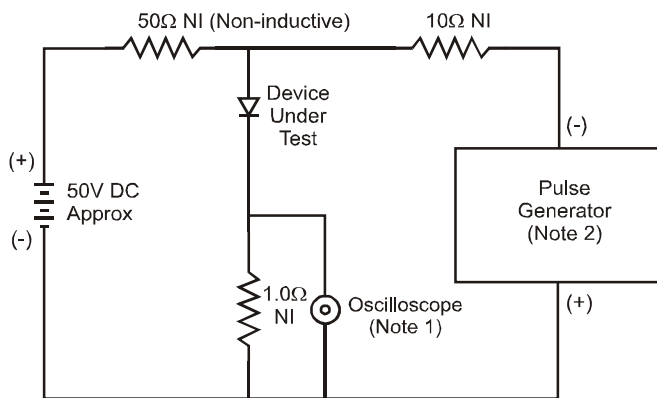


Fig. 4 Typical Reverse Characteristics



Notes:

1. Rise Time = 7.0ns max. Input Impedance = 1.0M Ω , 22pF.
2. Rise Time = 10ns max. Input Impedance = 50 Ω .

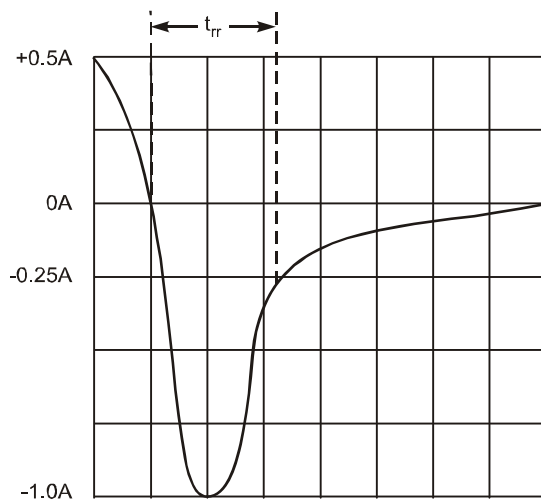


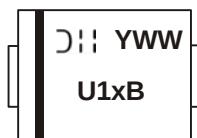
Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

Ordering Information (Note 8)

Part Number	Case	Packaging
MURS140-13-F	SMB	3000/Tape & Reel
MURS160-13-F	SMB	3000/Tape & Reel

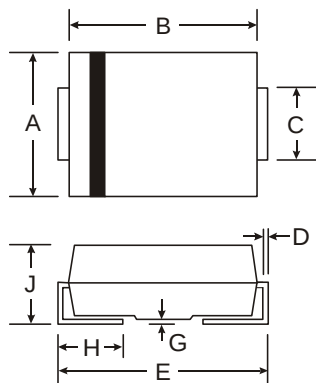
Notes: 8. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



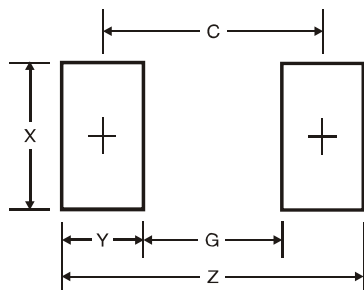
U1xB = Product type marking code
 U1GB = MURS140
 U1JB = MURS160
 DI = Manufacturers' code marking
 YWW = Date code marking
 Y = Last digit of year (ex: 2 for 2002)
 WW = Week code (01 to 53)

Package Outline Dimensions



SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout



SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
X	2.3
Y	2.5
C	4.3

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